

Appl. No. 09/855,820
Amdt. dated November 11, 2003
Reply to Office Action of August 15, 2003

PATENT

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1.-26. (canceled)

Claim 27. (currently amended) ~~The method of claim 26~~ A method for forming a semiconductor die package, the method comprising:

(a) forming a carrier, wherein forming the carrier comprises providing a metal layer, and forming a plurality of bumps in the metal layer, wherein the formed bumps are capable of being electrically coupled to conductive regions of a circuit substrate, and wherein forming the plurality of bumps comprises stamping; and

(b) attaching a semiconductor die to the metal layer after forming the plurality of bumps wherein attaching comprises:

attaching the semiconductor die to a die attach region of the carrier, and wherein the plurality of bumps is disposed around the semiconductor die.

Claim 28. (canceled)

Claim 29. (currently amended) ~~The method of claim 24~~ A method for forming a carrier for a semiconductor die package, the method comprising:

(a) providing a metal layer; and

(b) forming a plurality of bumps in the metal layer, wherein the formed bumps are capable of being electrically coupled to conductive regions of a circuit substrate, and wherein forming the plurality of bumps comprises stamping, wherein the bumps each have a conical shape.

Claim 30. (currently amended) The method of claim 24 ~~29~~ wherein the metal layer comprises copper.

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Claim 31. (currently amended) The method of claim 24 29 wherein the bumps in the plurality of bumps are disposed in an array.

Claim 32. (currently amended) The method of claim 24 29 wherein the bumps in the plurality of bumps are arranged around a the die attach region and have heights greater than the thickness of the semiconductor die.

Claim 33. (canceled)

Claim 34. (currently amended) The method of claim 24 29 wherein the metal layer includes one or more sublayers of material on a base metal.

Claim 35. (canceled)

Claim 36. (currently amended) The method of claim 24 29 wherein each bump has a conical angle of about 40 degrees of more.

Claim 37. (currently amended) The method of claim 24 29 wherein the plurality of bumps are formed simultaneously in the metal layer.

Claim 38. (new) The method of claim 27 wherein the metal layer comprises copper.

Claim 39. (new) The method of claim 27 wherein the bumps in the plurality of bumps are disposed in an array.

Claim 40. (new) The method of claim 27 wherein each bump has a conical angle of about 40 degrees of more.

Claim 41. (new) The method of claim 27 wherein the metal layer includes one or more sublayers of material on a base metal.

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Claim 42. (new) The method of claim 29 wherein the metal layer comprises a die attach region and wherein the bumps are formed around the die attach region.